



# Customer Technical Update With LAYTEC



Friday 13<sup>th</sup> December 2024 commencing 09:30

TIME	TOPIC	PRESENTER
10 min	<b>Welcome, Introduction Company Overview</b> <ul style="list-style-type: none"><li>• Corporate Organization and Oxford Instruments Plasma Technology.</li><li>• Workshop objective.</li></ul>	Gohda-san - Oxford Instruments
30 min	<b>InP and GaAs lasers – III-V Material Processing</b> <ul style="list-style-type: none"><li>• Production solution for etching of InP transceivers and GaAs VCSEL.</li><li>• Etch III-V etching process overview for R&amp;D.</li></ul>	Dr Ligang Deng - Oxford Instruments
30 min	<b>SiC PE – Material Processing</b> <ul style="list-style-type: none"><li>• Plasma etch and deposition solutions for current and next generation SiC power devices.</li><li>• SiC substrate Epi ready cost reduction for 150mm and 200mm wafers with plasma polishing.</li></ul>	Ian Wright - Oxford Instruments
15 min	<b>Coffee Break sponsored by Hakuto</b>	
30 min	<b>GaN PE/RF – Atomic Scale Processing</b> <ul style="list-style-type: none"><li>• Production-qualified Plasma Atomic Layer Deposition for GaN HEMT passivation.</li><li>• Low damage, reliable etch processes for p-GaN HEMT and recessed MISHEMT manufacturing.</li></ul>	Dr Aileen O'Mahony - Oxford Instruments
20 min	<b>Endpoint solutions</b> <ul style="list-style-type: none"><li>• Leading endpoint accuracy.</li><li>• End pointing materials.</li></ul>	Dr Yuto Tomita - Laytec
10 min	<b>Wrap up and next steps</b> <ul style="list-style-type: none"><li>• Q&amp;A</li><li>• Further engagement.</li></ul>	Robert Gunn - Oxford Instruments
60 min	<b>Coffee light - refreshments</b>	